

Part-No.

M11E7002



Luminious Flux

(lm)





Features

Highest Luminous Flex Long Lifetime Operation Super Energy Efficency Superior UV Resistance Superior ESD protection

Absulut Maximum Ratings (Ta=25°C)

Items	Symb ols	Absulut maximum Rating	Unit
	015	Warm White	
Power Dissipation	Pd	800	mW
Forward Current	lf	200	mA
Peak Forward Current	lfp	250	mA
Reverse Voltage	Vr	5	V
LED Junction Temperature	Tj		°C
Operating Temperature	Topr	-30°C ~ +85°C	°C
Storage Temperature	Tstg	-40°C ~ +100°C	С°

* Pulse width \leq 0,1msec duty \leq 1/10

-		Ai	node(+)		Cathode(-)				Tops F	Power LED
		I								Part No.:	M11E7002
DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010	Customor	
APPD:	Schumi			FINISH	Jamy		Shee	t No.	1 from 10	Customer:	

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t of forward voltage +/-0.1V

Max

4.0

Forward Voltage

(V)

Min

3.3

Image: Construction of the second second

Tolerance of measurement of luminous flux : +/-15%
Tolerance of measurement of dominant Wavelength : +/-1nm
Tolerance of measurement of CCT (Correlated color temperature +/- 200K

Тур

20

Rever-

se Cur-

rent

(µA)

max

10

50%

Power

Angle

Тур

120

4. Tolerance of measurement of forward voltage +/-0,1V

Dominant

Wavelength (nm)

or CCT(K)

Тур

3200

Min

2800

Technical Dimensions

Typical Electrical & Optical Characteristics (IF=350mA and Ta=25°C)

Min

15

BIN GUIDE / HIGH POWER









CCT Range

Max

Min

r of LED Light

Code	Lu	uminous	Flux Ran	ge	Code	Lu	uminous	Flux Ran	ge	1			Co	do		CCT F	ange		Co	do
Code	m	in	m	ax.	Code	m	in	m	ax.	%				ue	N	lin	-	ax	00	de N
А		1		2	P2	7	0	8	0	- 15%			A	4		'00	29	00	N	1 4
В	2	2	2	,5	M1	8	0	g	0	is +/-			E	3	29	000	31	00	N	5 ا
С	2	,5	3	,2	M2	9	0	1	00	i xn			()	31	00	33	00	P	° 5
D	3	,2		4	N1	1(00	1	10	measurement of luminous Flux			Ε)	33	800	35	00	G	2 6
Е	4	4		5	N2	1	10	1:	20	nor			E	Ξ	35	500	37	00	R	8 6
F	į	5	6	,2	P1	1:	20	1;	30	,ier			F	-	37	'00	39	00	S	5 7
G	6	,2	7	,7	P2	1:	30	1.	40	of Ir			(3	39	000	41	00	Т	7
Н	7	,7	9	,6	Q1	14	40	1:	50	ent			ŀ	1	41	00	43	00	U	J 8
J	9	,6	1	2	Q2	1:	50	1	60	rem				J	43	800	45	00	V	/ 9
K		2	1	5	R1		60	1	70	asul			ł	<	45	500	47	00	N	V 10
L1		5	1	9	R2		70	1	80	me			l	-	47	'00	49	00		
L2		9		24	S1		80	2	00	of			Tolerand	e of mea	suremen	t of CCT is	s +/-100ł	Κ.		
M1		24		30	S2		00		20	Tolerance										
M2		0		10	T1		20		40	lera										
N1		0		50	T2		40		60	To										
N2		0		60	U1	2	50	2	80											
P1	6	0		0																
			В	I	H	G	/E		F	,	Y	Q	/P	R	/U	_				
	Code	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	nent of +/-1nm				
	00	450	455	490	495	515	520	560	565	580	583	600	605	620	625	neni +/-				
	01	455	460	495	500	520	525	565	570	583	586	605	610	625	630	uren is ר				
	02	460	465	500	505	525	530	570	575	586	589	610	615	630	635	easu				
	03	465	470	505	510	530	535	575	580	589	592	615	620	635	640	f mé /ele				
	04	470	475	510	515	535	540			592	595			640	645	e of wav			F	
	05	475	480			540	545			595	598			645	650	Tolerance of measurement of dominant wavelength is +/-1nm				
	06	480	485			545	550							650	655	oler minä				Тор
	07	485	490			550	555							655	660), T				
	8					555	560							660	665					Part No.:
DR	RW:		son	C⊢	IKD	Wil	son		TL: ISH		son my	TOLE	RANCE	Ma	son	DA	TE	12.07.20 2 from		Customer:
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Tops Power LED

M11E7002



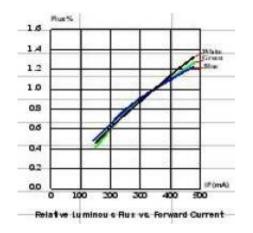




The Power of LED Light

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Typical Electrical / Optical Characteristics Curves (Ta=25°C Unless otherwise noted)



Ring-American

RING-ANDER CW

Ring-American Ring-Amorican

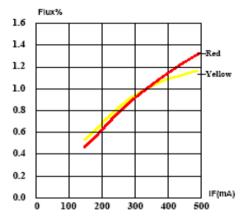
1F(mA) 400 350

22

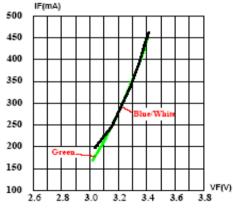
21

10

DRW: APPD: **Current Derating Curves**

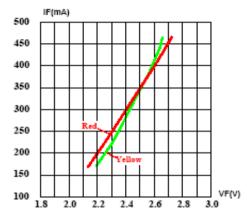


Relative Luminous Flux vs. Forward Current



2.6 2.8	3.0 3.2 3.4	3.6 3.8	
Forward	Current vs. Forwar	d Voltage	_
Code	Forward Vo	oltage Rank	
Code	Min.	Max.]
А	1,6	1,8	1
В	1,8	2,0	1
С	2,0	2,2	1
D	2,2	2,4	1
E	2,4	2,6	1
F	2,6	2,8	1
G	2,8	3,0]
Н	3,0	3,2]

Tolerance of measurement of forward voltage is +/-0,1V



Forward Current vs. Forward Voltage

Code	Forward Vo	oltage Rank
Code	Min.	Max.
J	3,20	3,40
К	3,40	3,60
L	3,60	3,80
М	3,80	4,00
Ν	4,00	4,20
Р	4,20	4,40
Q	4,40	4,60
R	4,60	4,80

25 50	75 100	125 15							Tops P	ower LED
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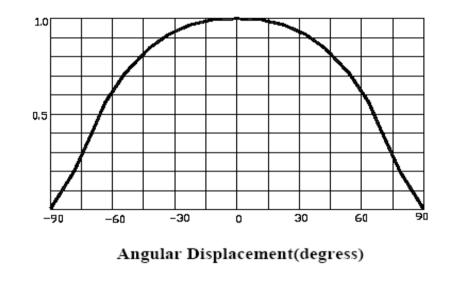
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120



Typical Representative Spatial Radiation Paddern of single LED

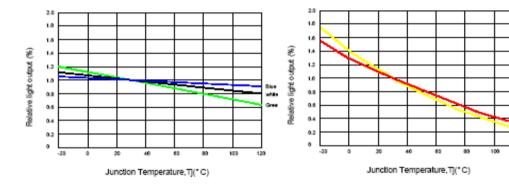




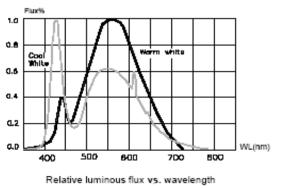


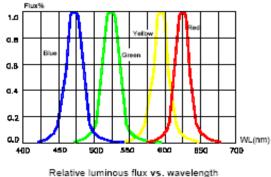
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Light Output Characteristics



Wavelength Characteristics





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Handling Informations

- 4. The outer diameter of the TOP LED pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although ist characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of th LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools



2. Do not directly touch or handle the silicone lens surfance. It may damage the internal circuitry.

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3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratsch the silicone lens or damage the internal circuitry.



Tops Power LED

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Moisture Proof Packing

In Order to prevent moisture absorption into DIAMOND = TOP LED / XEON POWER during the transportation and storage. DIAMOND TOP-LED / XEON-POWER LED is packed in a moisture barrier bag. Desiccants and humidity indicator are packed together with DIAMOND TOP-LED / XEON-POWER LED as the secondary protection. The indication of humidity card provides the information of humidity within TOP Packing.

Storage

Shelf life in original sealed bag in storage condition of <40°C and 90% RH is 12 mounths. Baking is required whenever shelf life is expired. Before opening the packaging please check wether bag leak air or not. After opening the DIAMOND TOP-LED / XEON POWER LED must be storad under the condition <30°C and 60% RH. Under this condition DIAMOND TOP-LED / XEON POWER LED must be used (subject to reflow) within 24-hours after bag opening, and re-baking is required when exceeding 24 hours. For baking, place DIAMOND TOP-LED / XEON POWER LED in oven at temperature 75°C +/-5°C and relative humidity <10%RH, for 24 hours. Take out the material from packaging bag for re-bake. Do not open the door of oven frequently during the baking process.

Manual soldering (We do not recommend this method strongly).

No mechanical stress should be exerted on the resin portion of DIAMOND TOP-LED / XEON POWER during soldering.

Handling of DIAMOND TOP-LED / XEON POWER LED should be done when the package has been cooled down to below 40°C or less. This is to prevent the DIAMOND

TOP-LED / XEON POWER failures due the thermal-mechanical strss during handling.

Reflow soldering should not be done more than one time.

No stress should be exerted on the package during soldering.

Electrostatic Discharge and Surge current.

Electrostatic discharge (ESD) or surge current (EOS) may damage LED.

Precautions such as ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling DIAMOND TOP-LED / XEON POWER LED.

All devices, equipment and machinery must be prpertly grounded.

It is recommended to perform electrical test to screen out ESD failures in final inspection.

It is importate to eliminate the possibility of surge current during circuity design.

Heat Management

Heat management of DIAMOND TOP-LED / XEON POWER must be taken into into consideration during the design stage of DIAMOND TOP-LED / XEON POWER LED application. The current should be de-rated appropriately by refering to the de-rating curve attached on each product specification.

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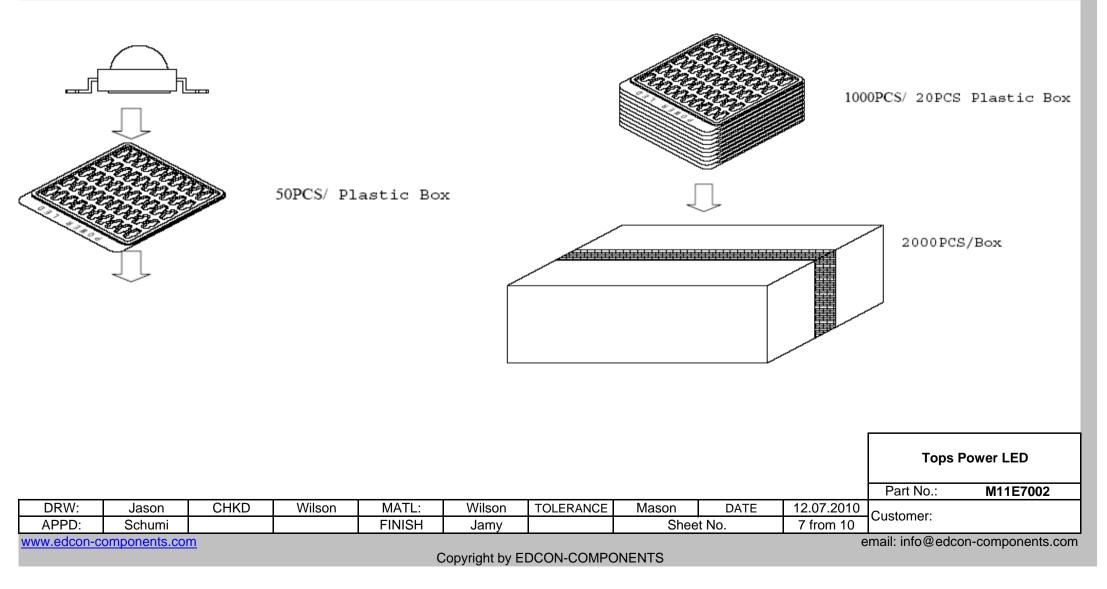








Packing Specifications









Ordering Informations

Serie	Color Code	ROHS	Packing				
M11E7002	WW	R	TR				

WW	R= ROHS	TR= TAPE
=	Conform	REEL
Warm White	N= NON	BU= Bulk-
	ROHS	Ware

_											Part No.:	M11E7002
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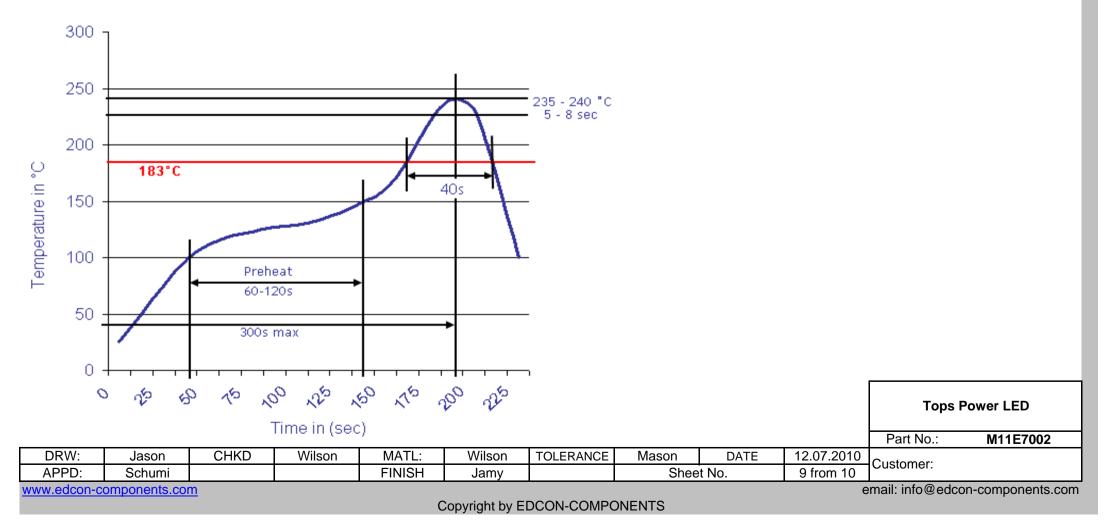






Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



Spectral Color Curve



DRW:

APPD:

CHKD

Jason

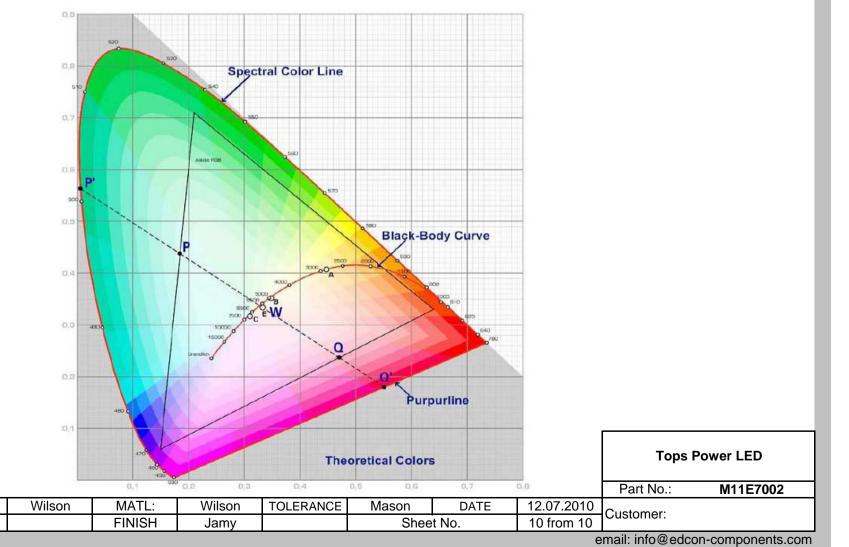
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